THIS SHEET HAS BEEN REPLACED

ABSTRACT OF THE DISCLOSURE

A mount head is connected to a negative pressure source and provided with solder ball suction holes formed in a matrix in the lower surface in accordance with a wiring pattern. A mask for covering the solder ball suction holes in portions where it is not necessary to mount solder balls is prepared for the mount head. The mask is used in accordance with necessity so as to carry out the mounting operation.

This Sheet Has Been Replaced